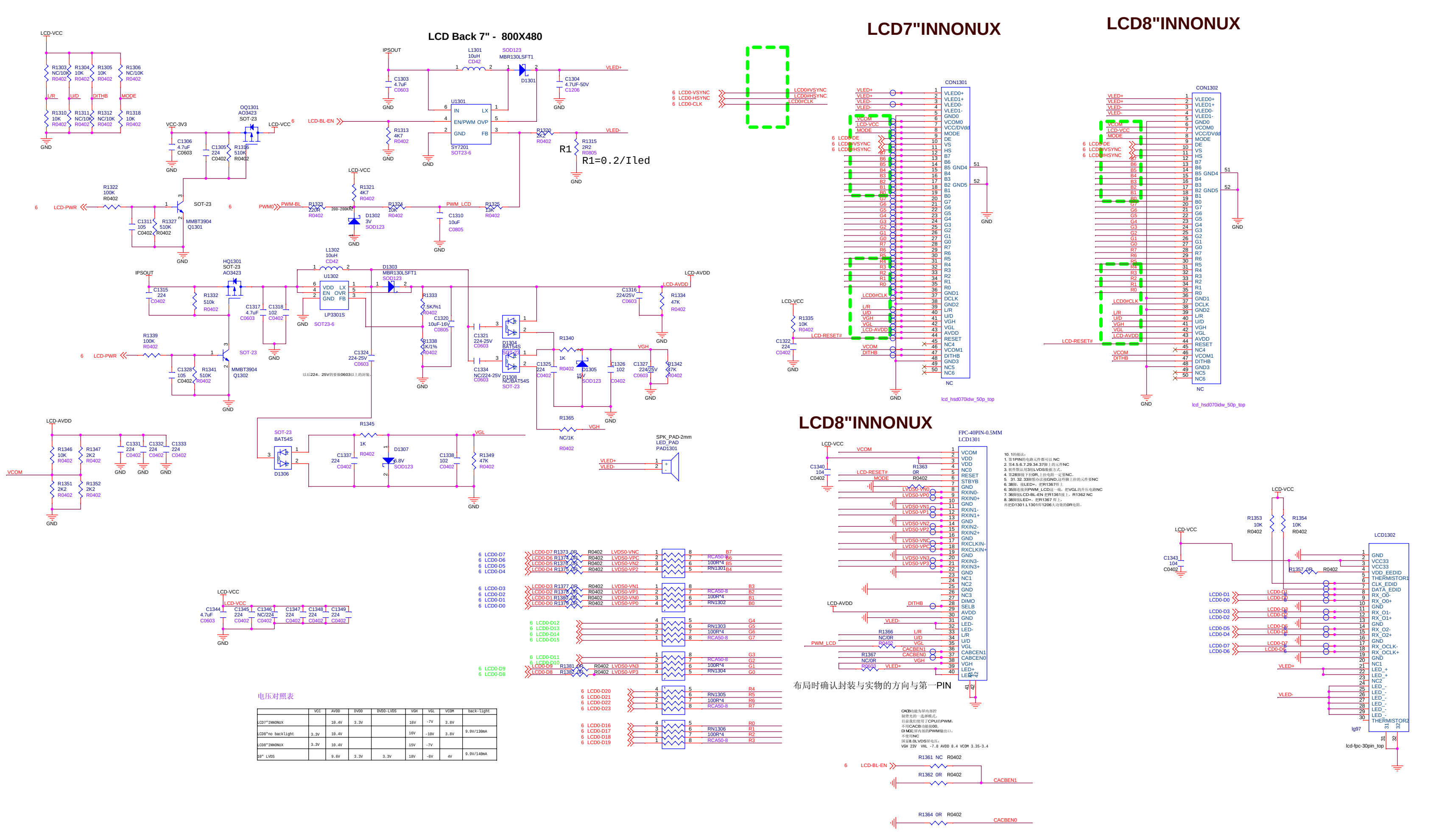
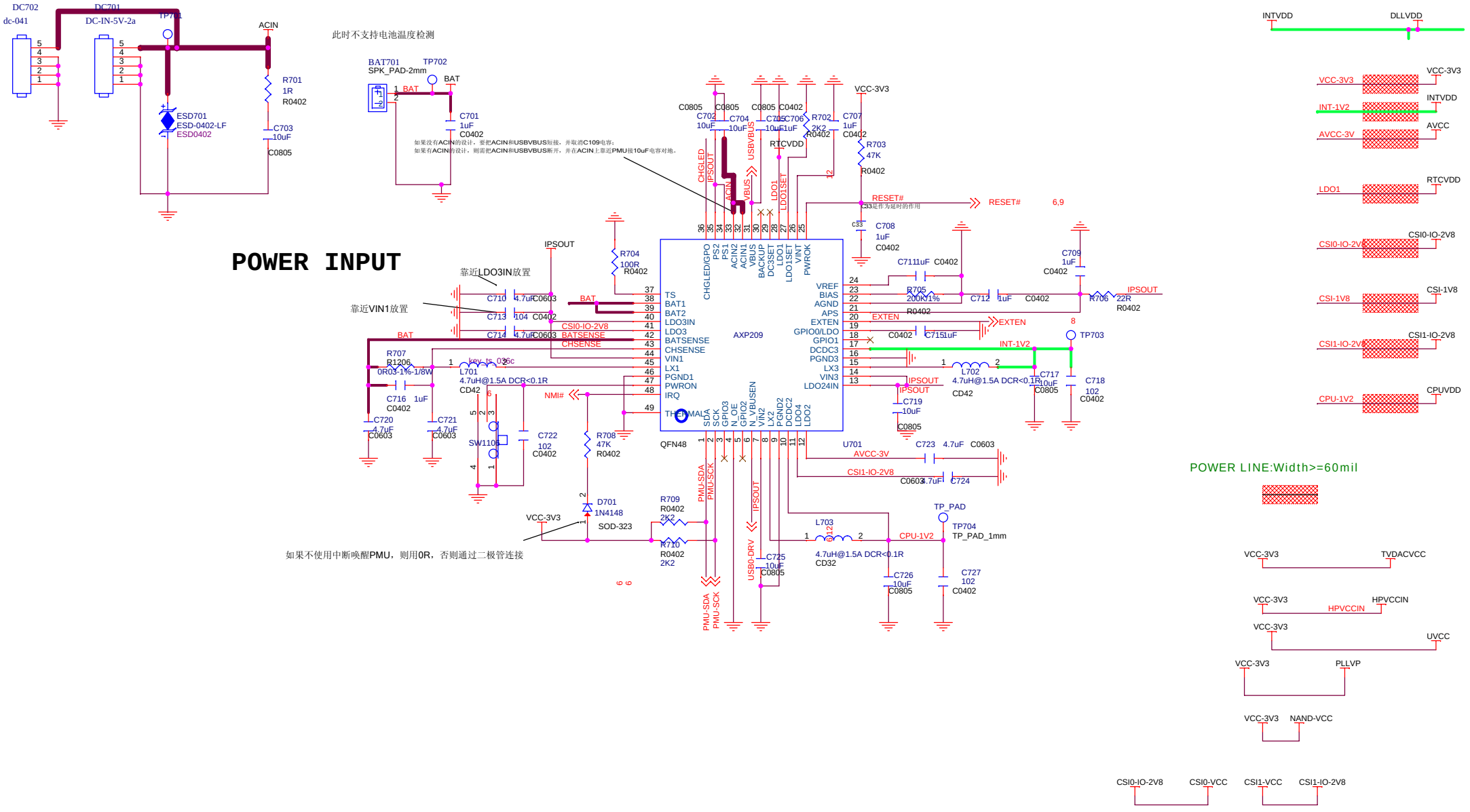
LCD



电压对照表

	VCC	AVDD	DVDD	DVDD-LVDS	VGH	VGL	VCOM	back-light
LCD7"INNONUX		10.4V	3.3V		16V	-7V	3.8V	
LCD8"no backlight	3.3V	10.4V			16V	-10V	3.8V	9.9V/130mA
LCD8"INNONUX	3.3V	10.4V			15V	-7V		
10" LVDS		9.6V	3.3V	3.3V	18V	-6V	4V	9.9V/140mA

POWER-PMU



Title	MAINCHIP_PAD_DDR3		
	POWER-PMU		
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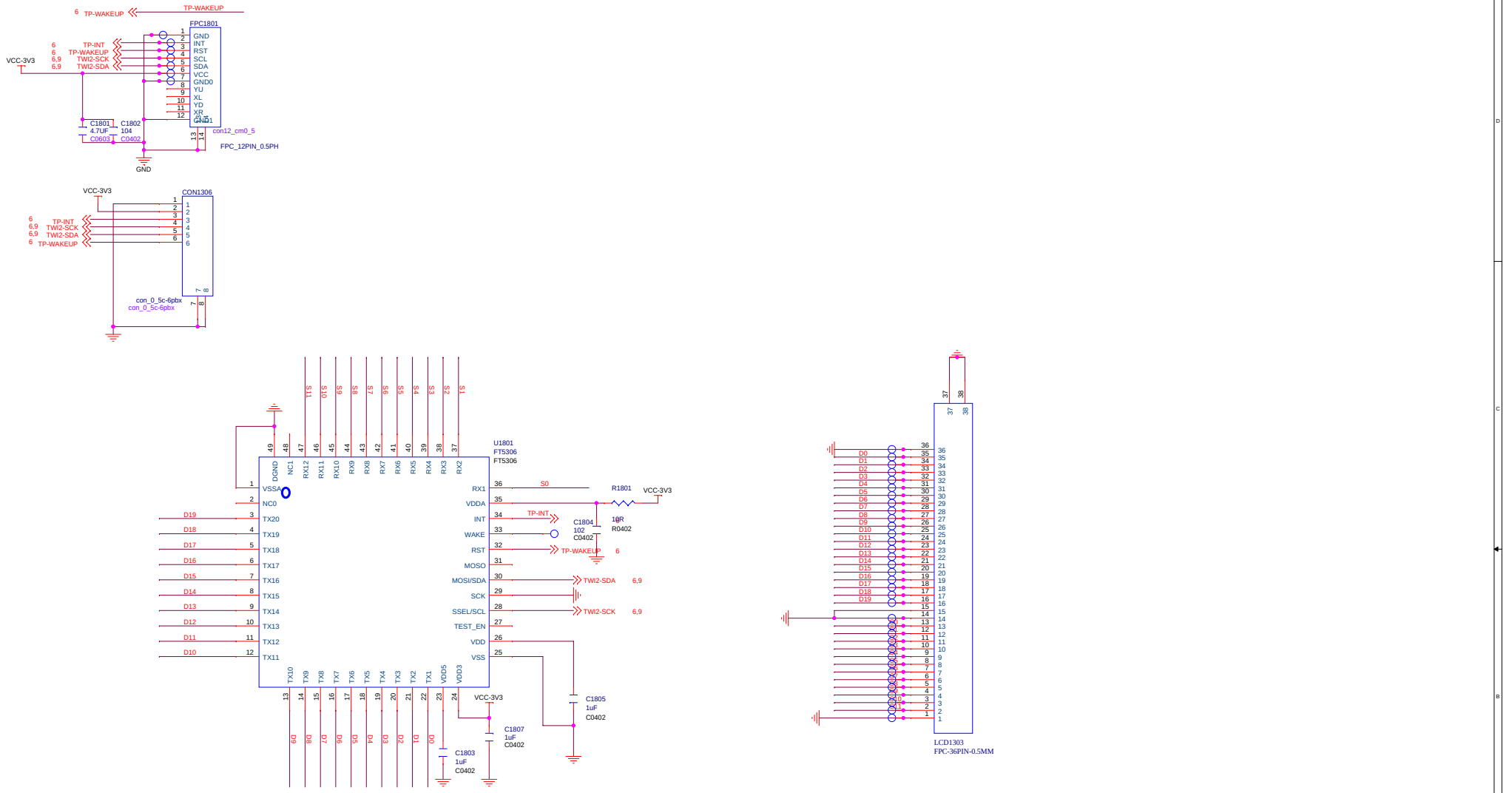

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Size: C	Document Number: <Doc>		Rev: <RevCode>
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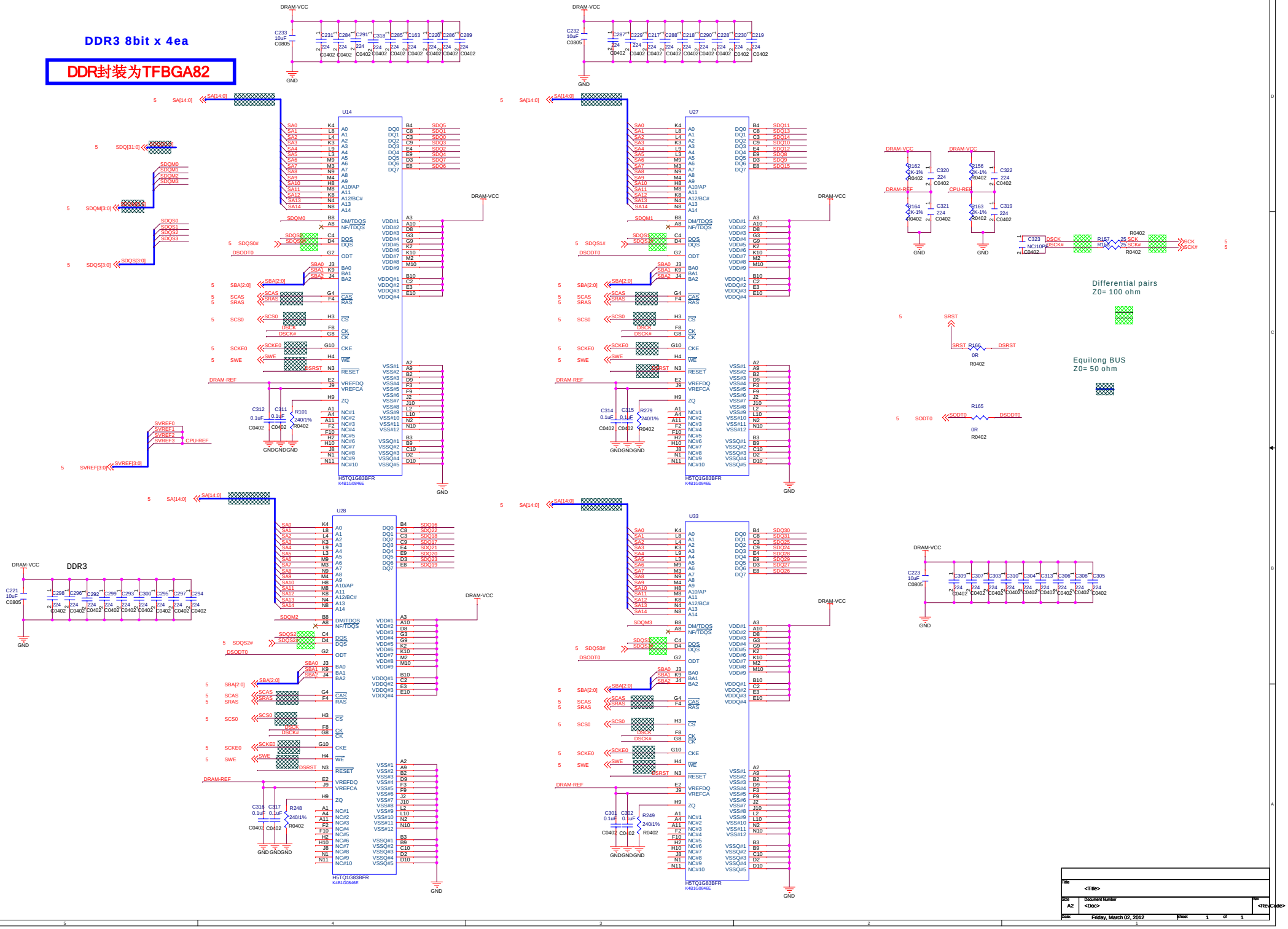
DDR3 8bit x 4ea

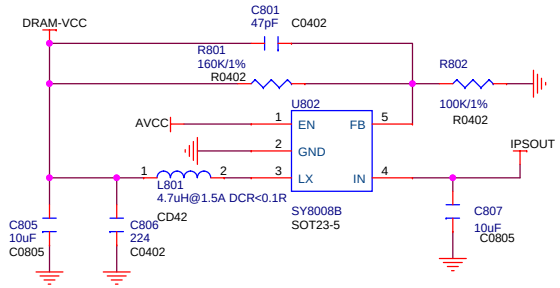
DDR封装为TFBGA82

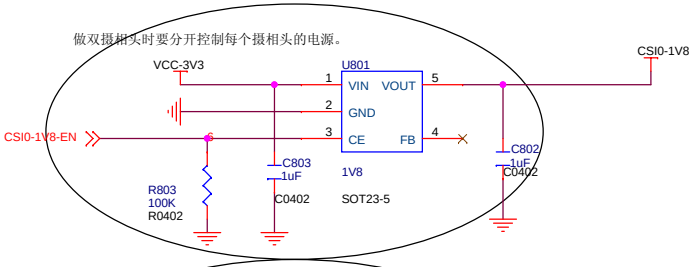


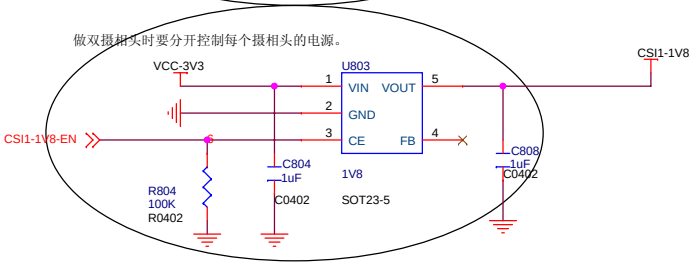
POWER-DC/DC

1. 电池充电电感： L1在value标注"4.7uH@1.5A DCR<0.1R"
2. LNT 1.2V电感： L2在value标注"4.7uH@1.5A DCR<0.1R"
3. CPU 1.2V电感： L3在value标注"4.7uH@1.5A DCR<0.1R"
4. VCC-3V3电感： L6在value标注"4.7uH@1.5A DCR<0.1R"
5. DRAM-VCC电感：L11在value标注"4.7uH@1.5A DCR<0.1R"
6. OTG升压电感： OL2在value标注2.2uH@2A DCR<0.1R

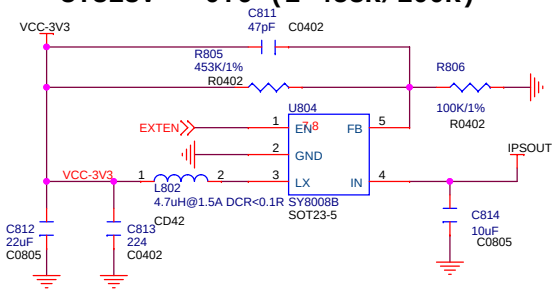
备注：xuH@xA表示在xA的电流下电感感量还满足xuH，DCR<0.1R表示电感直流电阻要小于0.1欧姆。
请将所有电感封装都改为CD43，CD32大多数情况下饱和电流不满足目前方案的应用要求。

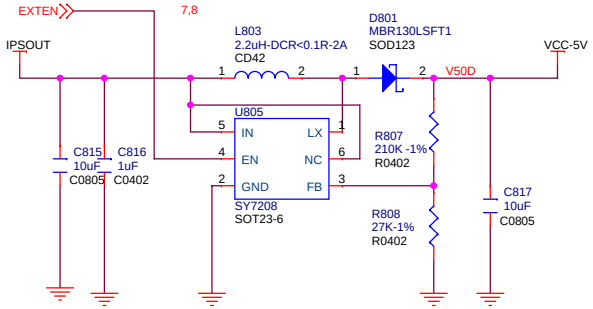






Vout = 0.6*(1+R1/R2)
3.318V = 0.6*(1+453K/100K)





Vout = 0.6*(1+R1/R2)　　实际输出控制在5.2V

5.26V = 0.6*(1+210K/27K)　　实际输出控制在5.26V

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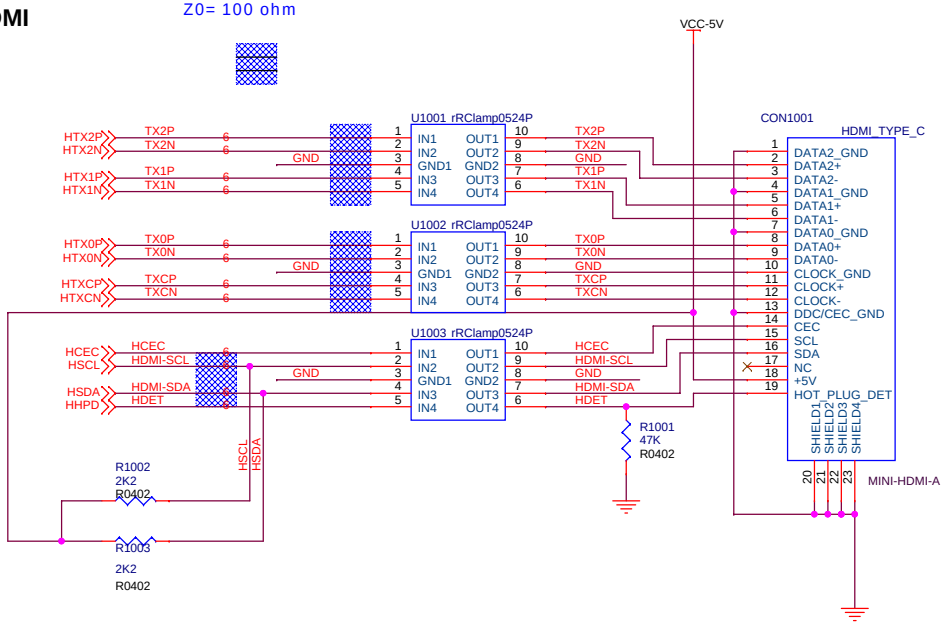
HDMI-CSI0

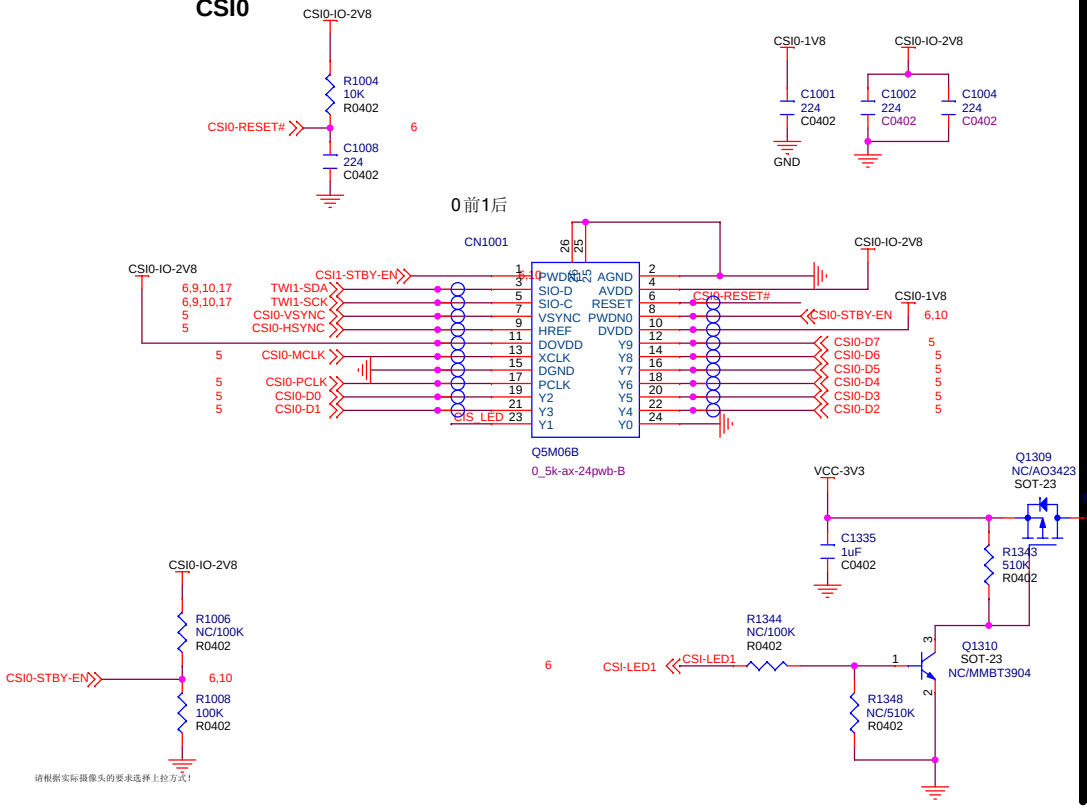
HDMI

HDMI

Differential pairs
Z0= 100 ohm

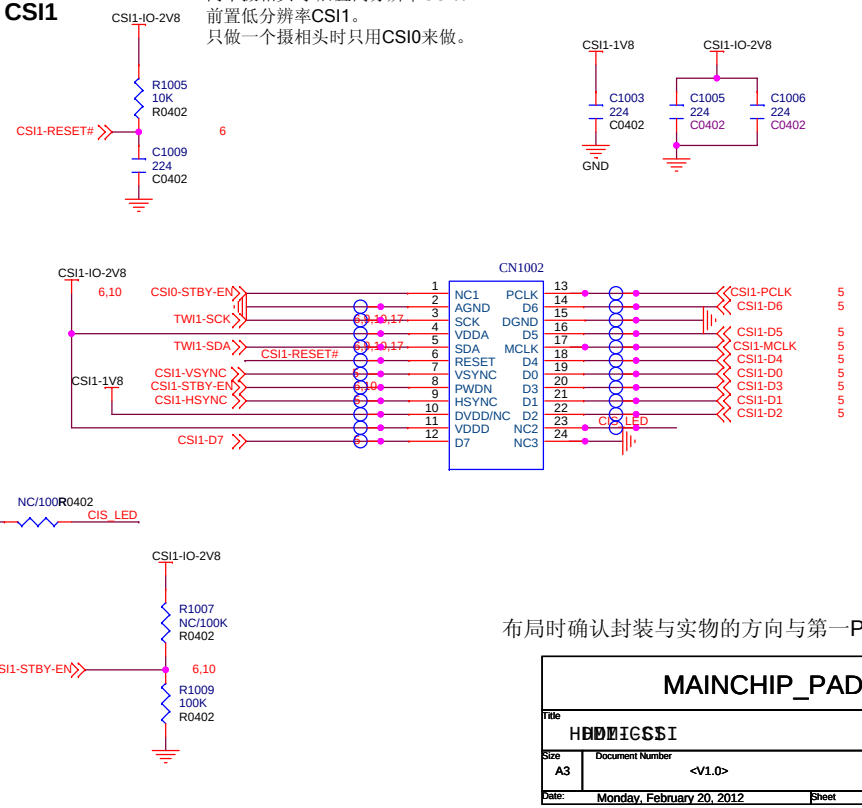


CSI0



CSI1

两个摄相头时:后置高分辨率CSI0，
前置低分辨率CSI1。
只做一个摄相头时只用CSI0来做。



布局时确认封装与实物的方向与第一PIN

MAINCHIP_PAD_DDR3

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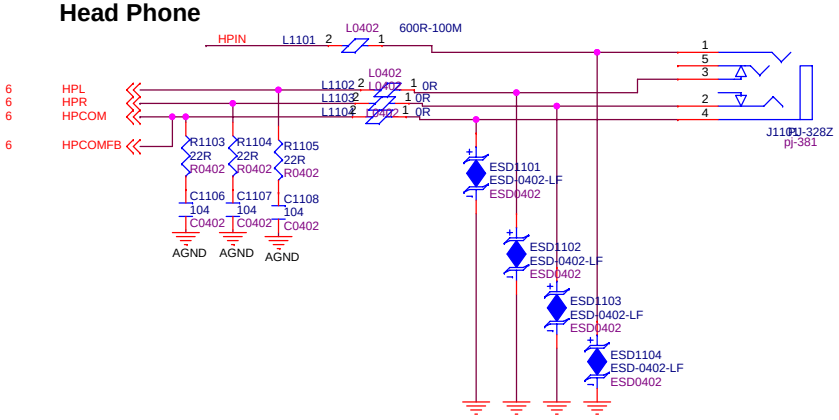
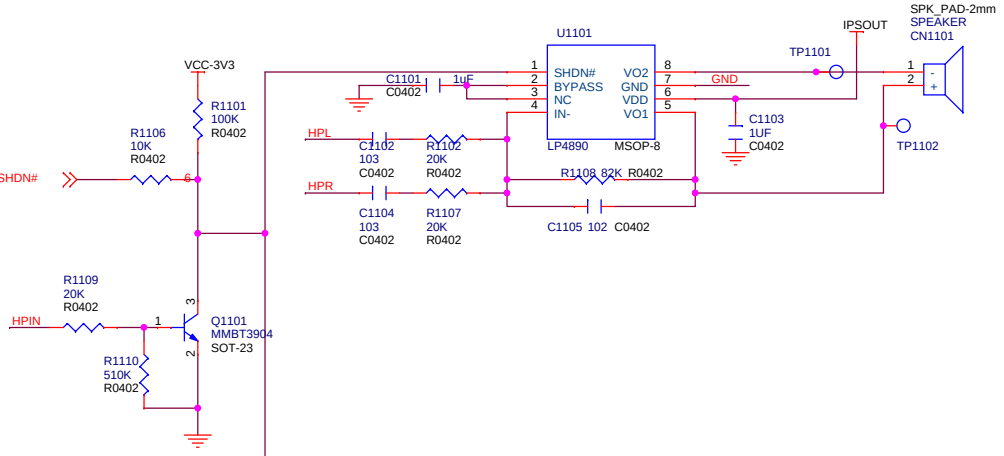
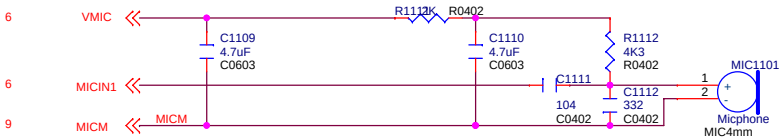
HP-KEY-MIC-IR-TVOUT

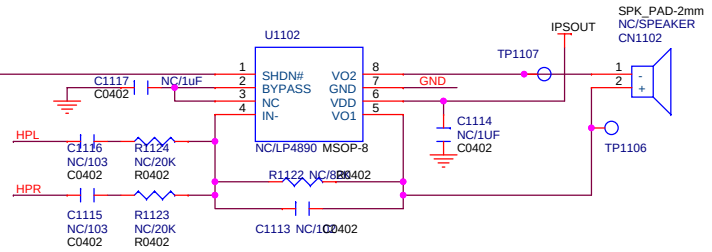
Head Phone



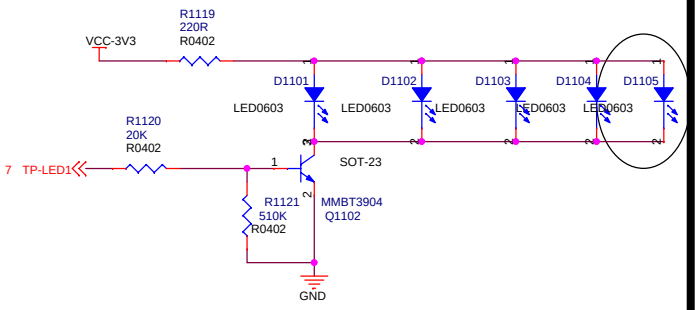


Microphone

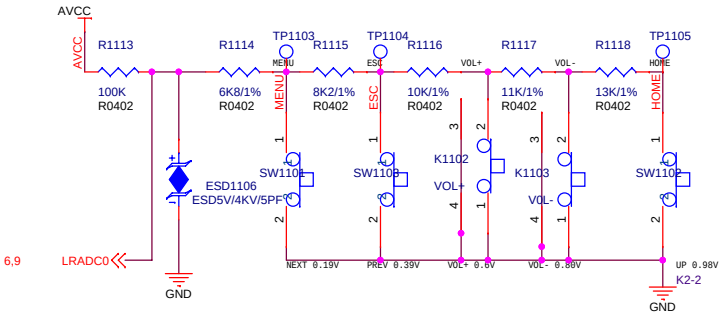


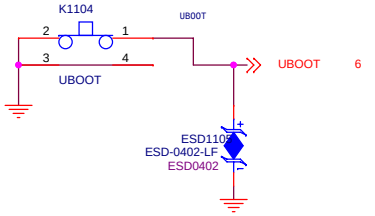


IR MODULE



KEY





此按键对应模具上的隐蔽小孔
用于固件升级，必须保留。

MAINCHIP_PAD_DDR3

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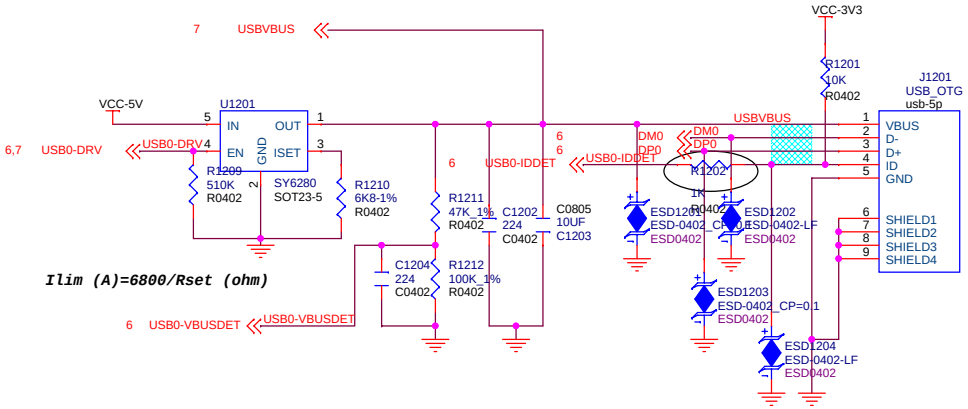
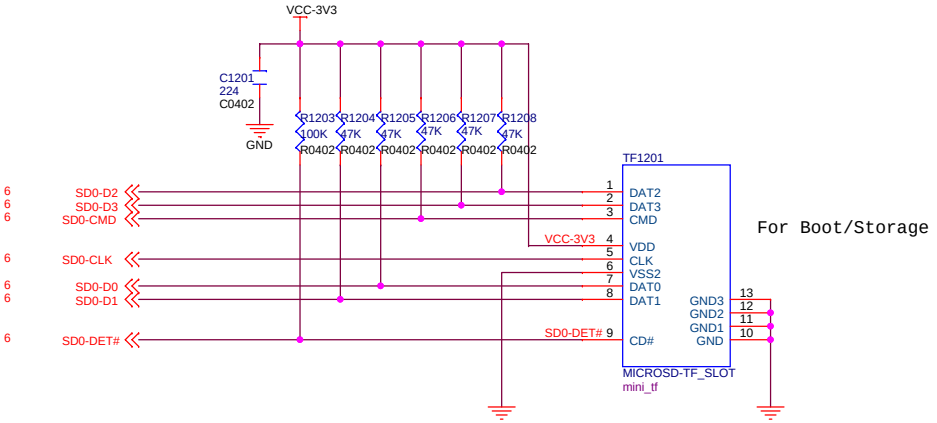
USB-CARD

USB_OTG



CARD0



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Title: USB-CARD			
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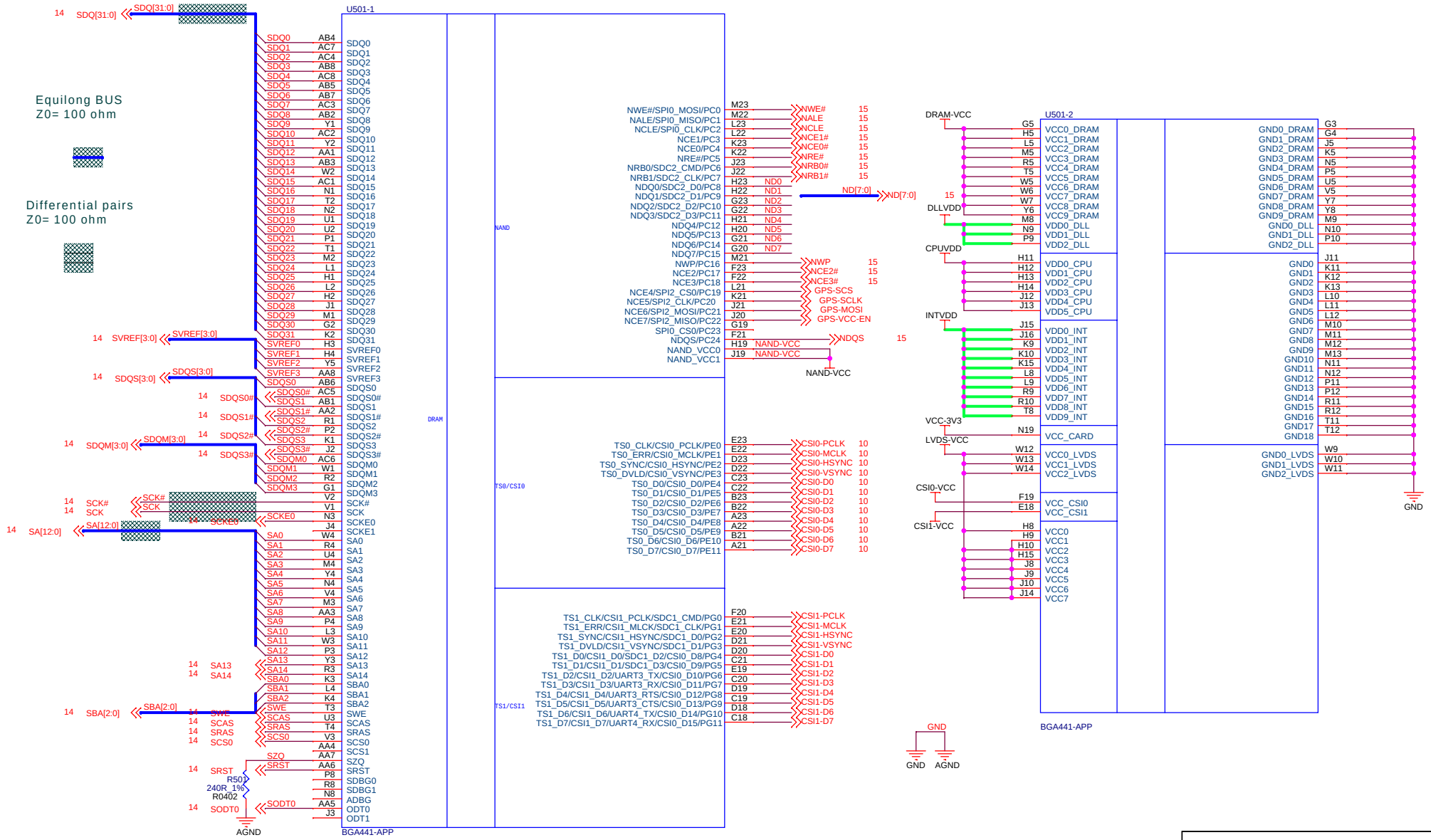
CPU1



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	CPU1
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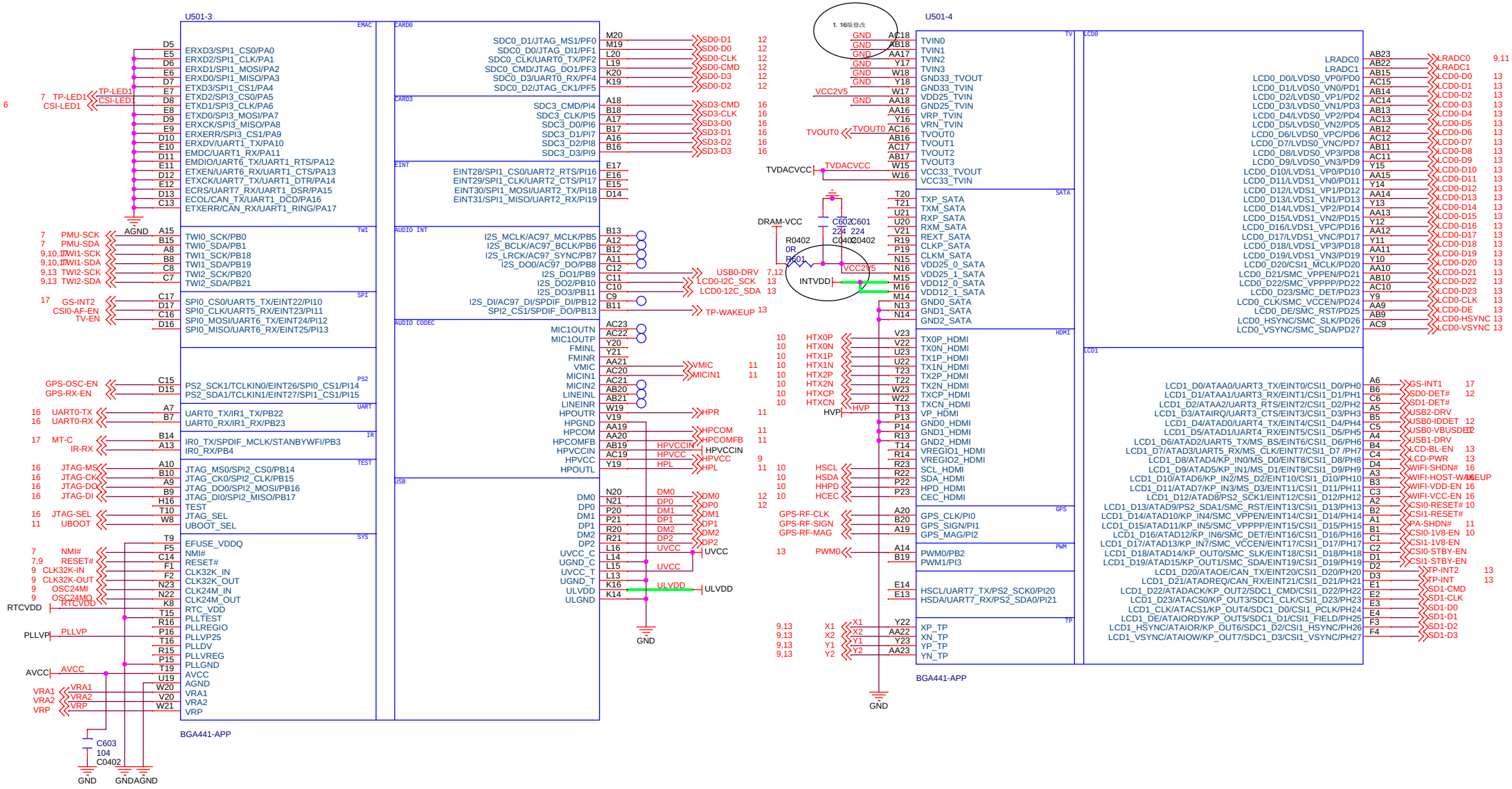
CPU2



Title	CPU2
Size	A3
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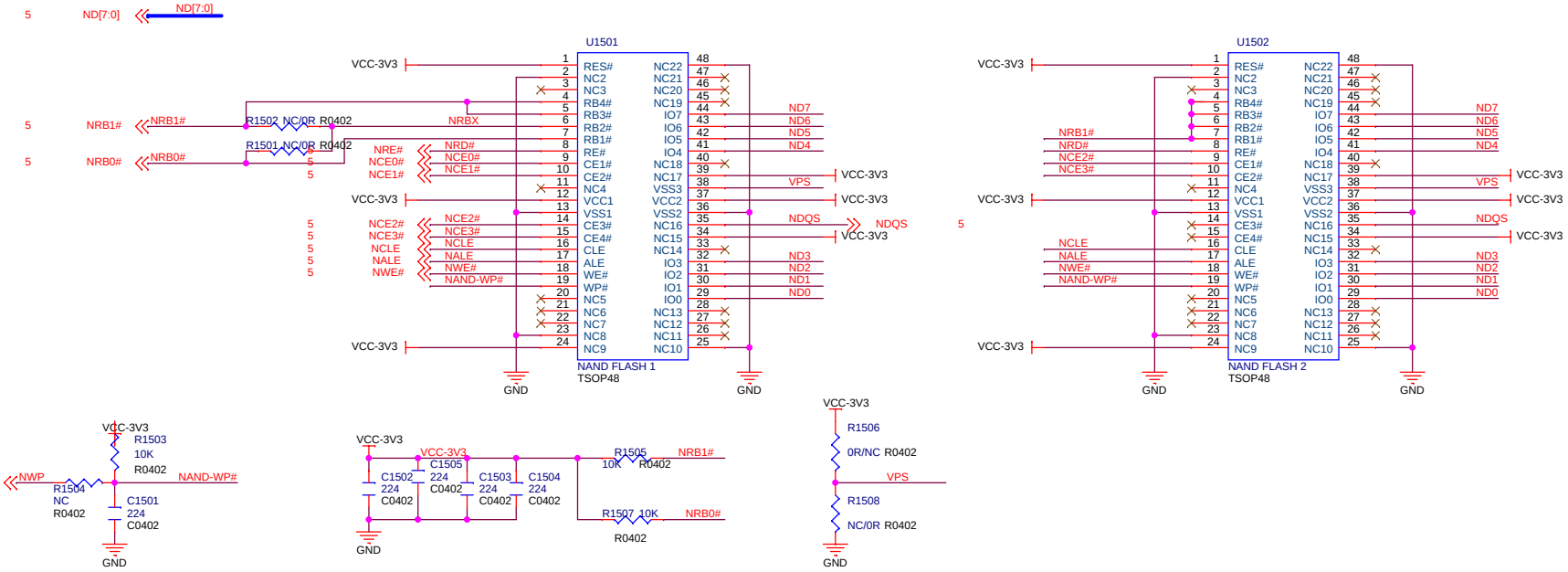
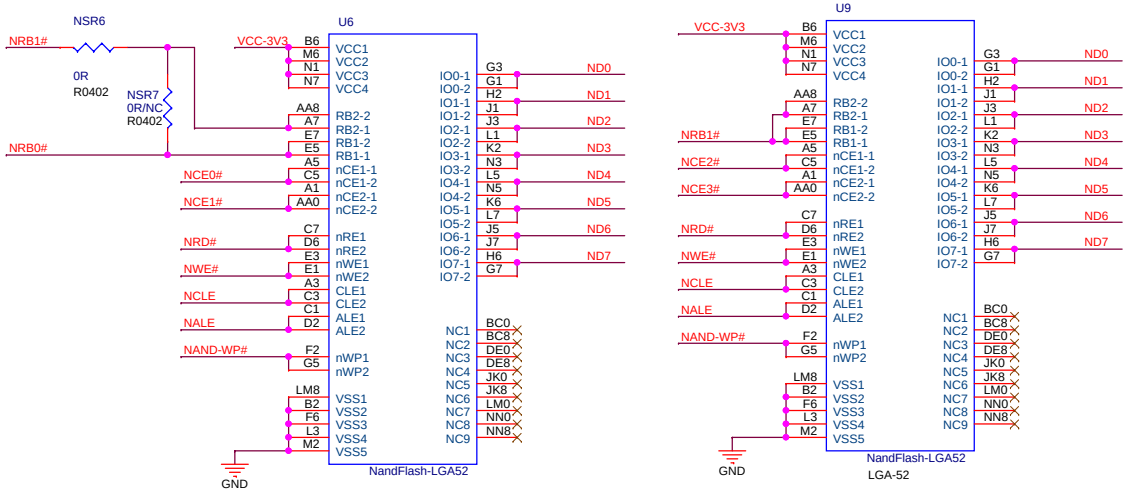
MAINCHIP_PAD_DDR3

NAND Flash

TSOP-48 Nand



LGA-52



(1) 接1片单片选Nand 时，NSR2、NSR1断开
(2) 接1片双片选Nand 时，连接NSR2，断开NSR1
(3) 接1片四片选Nand 时，连接NSR1，断开NSR2
(4) 接2片单片选或接2片双片选Nand时，连接NSR1，断开NSR2
(5) 接Intel、Toshiba、Samsung 2xnm TSOP Nand时， NSR4连接，NSR5断开；其它的NSR4断开，NSR5连接

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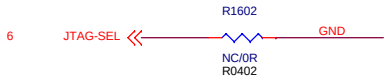
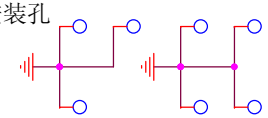
DEBUG

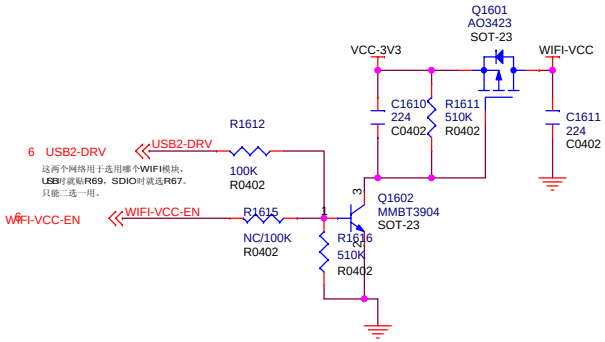


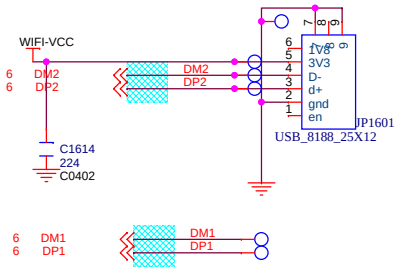
预留DEBUG测试点，以备调试使用

光学点位点

安装孔







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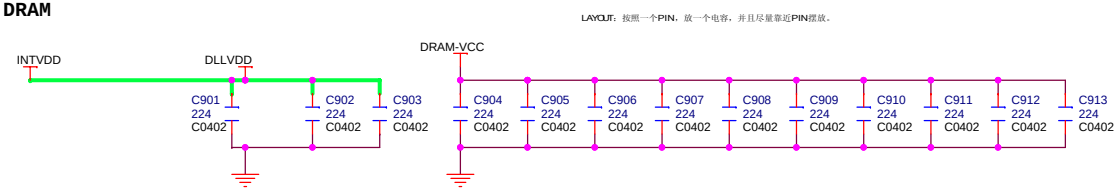
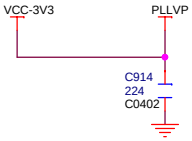
BESIDE CPU

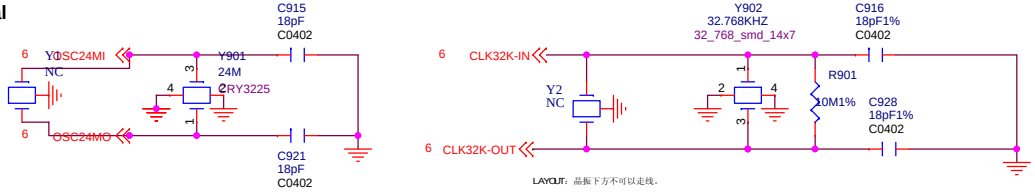
DRAM



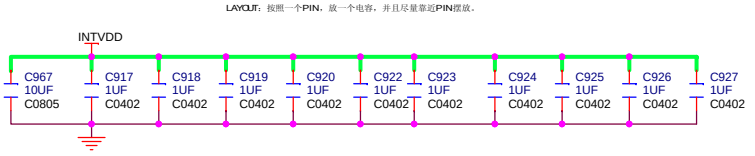
PLL



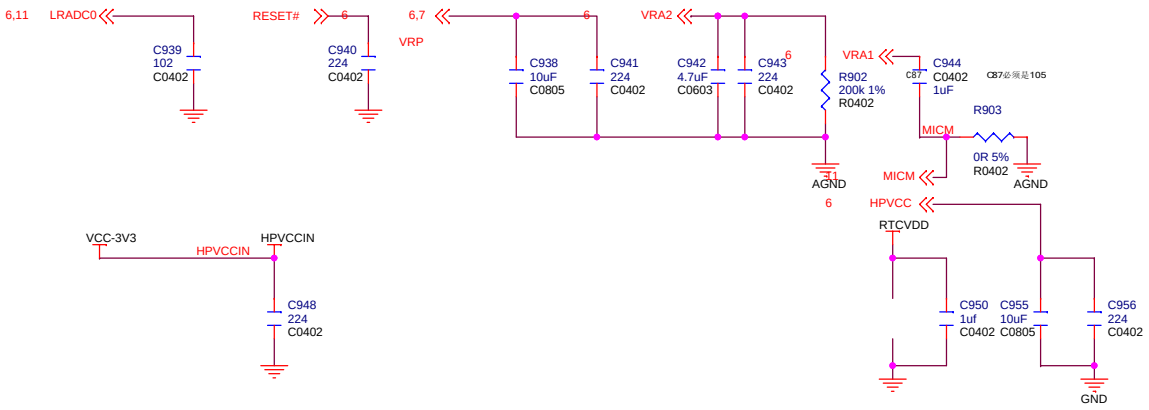
Crystal



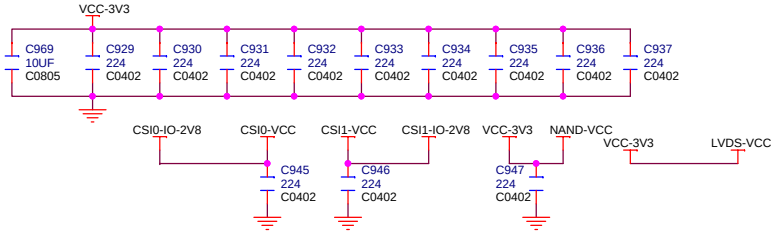
CORE



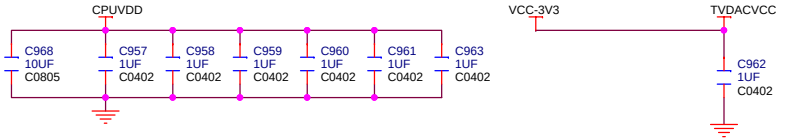
AUDIO&SYS&TP



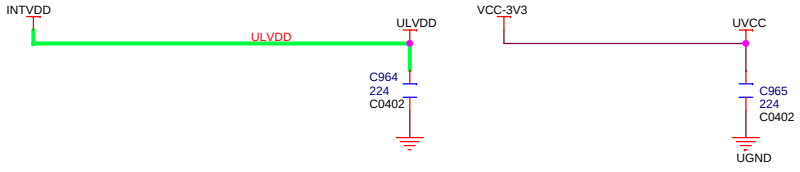
PIO-INTFACE



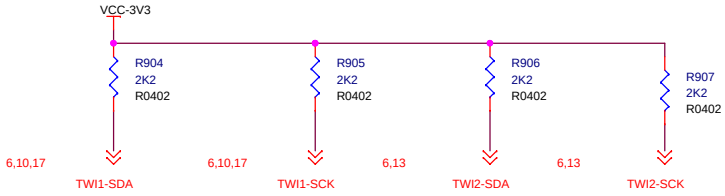
CPU&TV



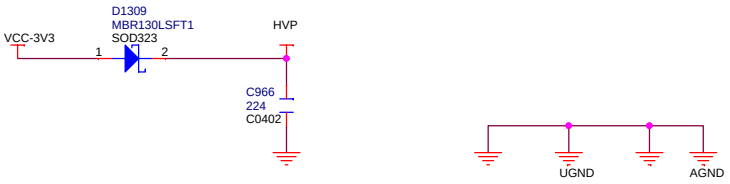
USB



TWI-PULLUP



HDMI



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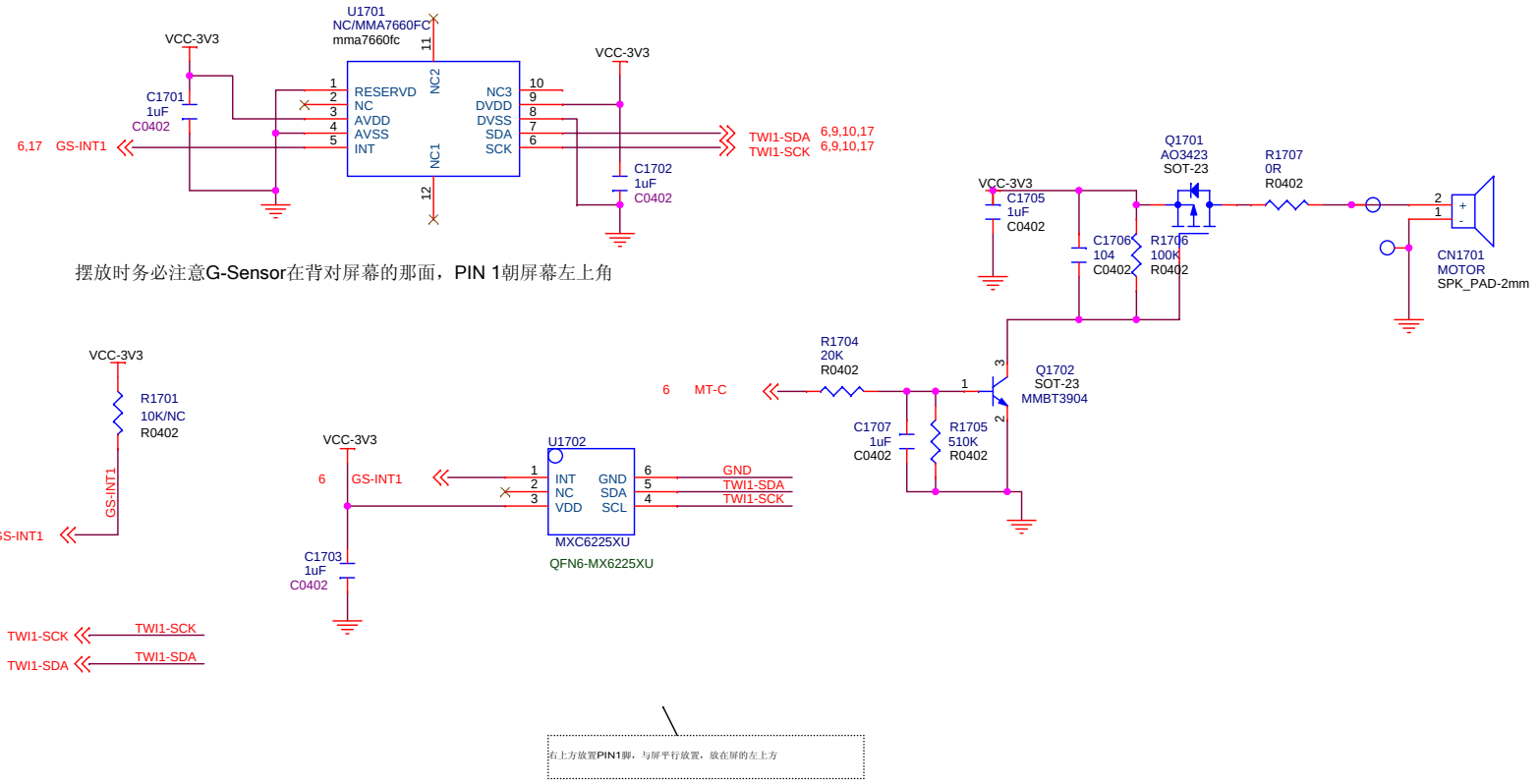
G-SENSOR



摆放时务必注意G-Sensor在背对屏幕的那面，PIN 1朝屏幕左上角

右上方放置PIN1脚，与屏平行放置，放在屏的左上方

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